YIELD ANALYSIS METHOD

ABSTRACT OF THE DISCLOSURE

A yield analysis method. First, a wafer having multiple dies is inspected to obtain wafer defect data containing defect information for every die in the wafer. Then a wafer map and an overall yield are generated according to the wafer defect data. The wafer map displays defective dies and defect-free dies in the wafer. Then, first and second systematic limited yields are calculated in accordance with the wafer defect data and the wafer map, wherein the first systematic limited yield is calculated excluding defective dies with localized distribution, and the second systematic limited yield is calculated excluding defective dies with repeated distribution. Then a random defect limited yield is determined in accordance with the overall yield, the first systematic limited yield, and the second systematic limited yield.

FIG. 3